



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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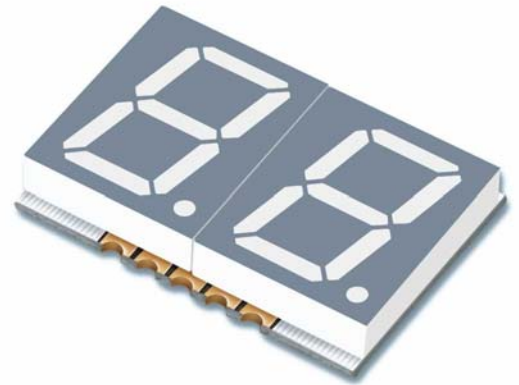
Technical Data Sheet

0.51" Dual Digit SMD Displays

ELSD-506SYGWA/S530-E2

Features

- Packaged in tape and reel for SMT manufacturing.
- Design flexibility(common cathode or anode).
- Categorized for luminous intensity.
- The thickness is thinner than traditional display.
- Pb free
- The product itself will remain with RoHS compliant version.



Descriptions

- The SMD type is much smaller than traditional type components, thus enabling smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.

Applications

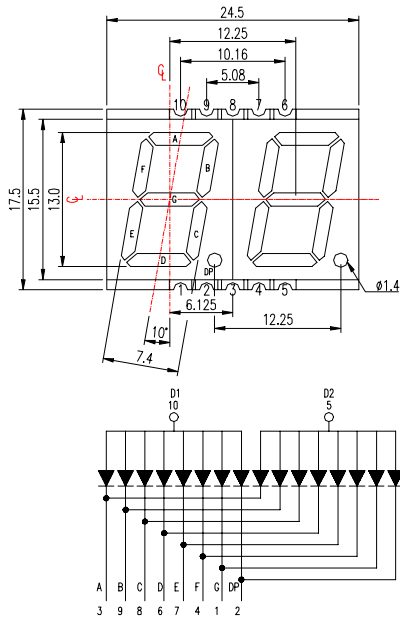
- Suitable for indoor use.
- Audio system.
- Set top box.
- Game machine.
- Channel indicator of TV.

Device Selection Guide

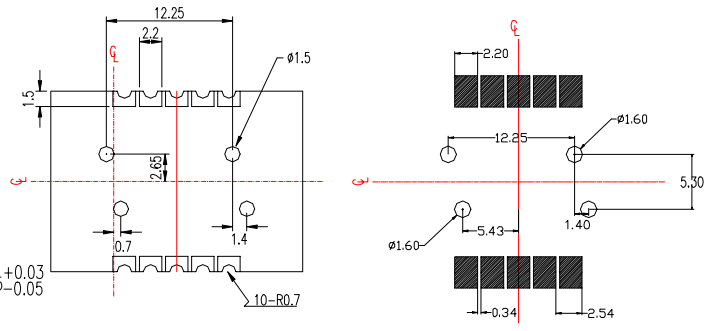
Chip		Face Color
Material	Emitted Color	
AlGaInP	Brilliant Yellow Green	Gray

ELSD-506SYGWA/S530-E2

Package Dimensions



Land Pattern(Recommend)



INTERNAL CONNECTION DIAGRM
 1 CATHODE G
 2 CATHODE DP
 3 CATHODE A
 4 CATHODE F
 5 COMMON ANODE D2
 6 CATHODE D
 7 CATHODE E
 8 CATHODE C
 9 CATHODE B
 10 COMMON ANODE D1

Notes:

- All dimensions are in millimeters, tolerance is 0.25mm unless otherwise noted.
- Above specification may be changed without notice. Supplier will reserve authority on material change for above specification.

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Units
Forward Current	I _F	25	mA
Pulse Forward Current ^{*1}	I _{FP}	60	mA
Operating Temperature	T _{opr}	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	°C
Soldering Temperature ^{*2}	T _{sol}	260	°C
Electrostatic Discharge	ESD	2000	V
Power Dissipation	P _d	100	mW
Reverse Voltage	V _R	5	V

Notes: *1:I_{FP} Conditions--Pulse Width ≤ 10msec and Duty ≤ 1/10.

*2:Soldering time ≤ 5 seconds.

Electro-Optical Characteristics (Ta=25°C)

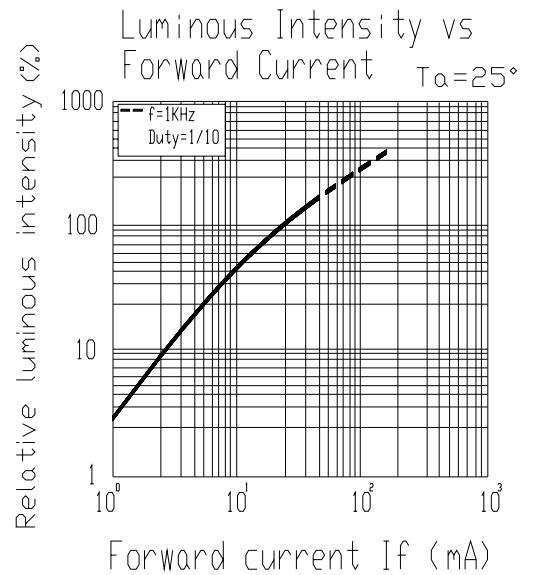
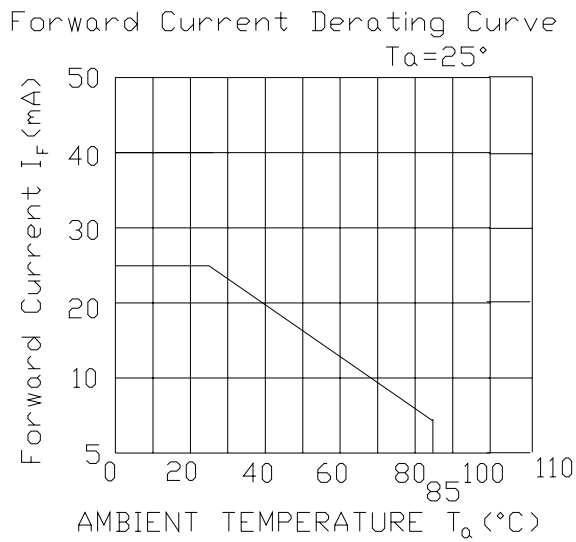
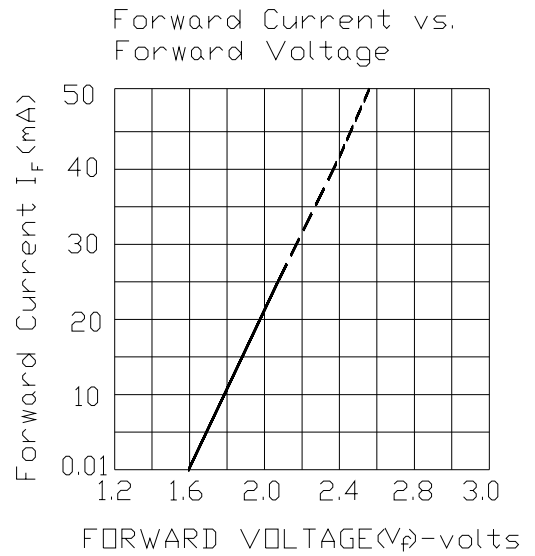
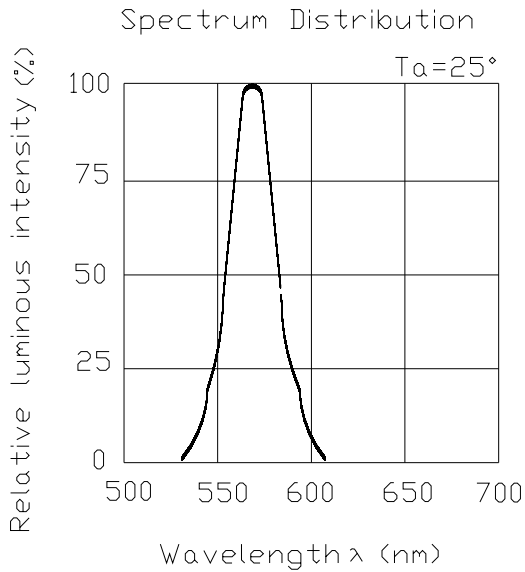
Parameter		Symbol	Min.	Typ.	Max.	Units	Condition
Forward Voltage		V_F	--	2.1	2.4	V	$I_F=10mA$
Reverse Current		I_R	--	--	10	μA	$V_R=5V$
Luminous Intensity	Per segment	I_V	5.6	9.5	--	mcd	$I_F=10mA$
	Per decimal point		2.0	4.3	--		
Peak Wavelength		λ_p	--	575	--	nm	$I_F=10mA$
Dominant Wavelength		λ_d	--	573	--	nm	$I_F=10mA$
Spectrum Radiation Bandwidth		$\Delta \lambda$	--	20	--	nm	$I_F=10mA$

Chromaticity Coordinates Specifications for Bin Grading (Unit: mcd)

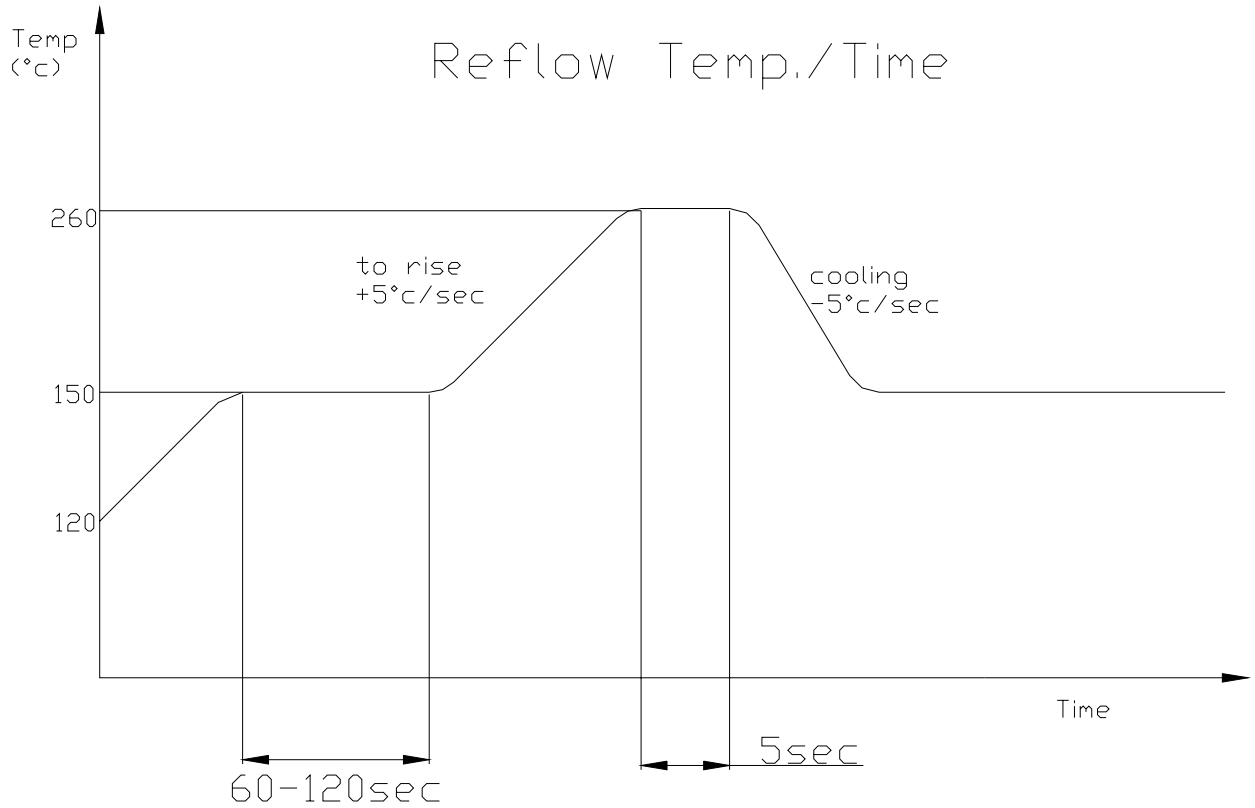
Rank	Min.	Max.	Rank	Min.	Max.
P	5.6	8.9	S	15.0	24.0
Q	7.8	12.5	T	21.0	34.0
R	11.0	17.6	--	--	--

Typical Electro-Optical Characteristics Curves

(SYG)



■ **Reflow Temp. / Time :**



■ **Soldering Iron :**

Basic spec is ≤ 5 sec when 260°C . If temperature is higher, time should be shorter ($+10^{\circ}\text{C} \rightarrow -1\text{sec}$). Power dissipation of iron should be smaller than 15 W , and temperature should be controllable. Surface temperature of the device should be under 230°C .

■ **Rework :**

1. Customer must finish rework within 5 sec under 260°C .
2. The head of iron can not touch copper foil.

Reliability test items and conditions:

The reliability of products shall be satisfied with items listed below.

Confidence level : 97%

LTPD : 3%

NO	Item	Test Conditions	Test Hours/Cycle	Sample Size	Failure Judgment Criteria	Ac/Re
1	Reflow	TEMP:260°C±5°C	5 SEC	76 PCS	$I_v \leq I_{vt} * 0.5$ or $V_f \geq U$ or $V_f \leq L$	0/1
2	Temperature Cycle	H : +100°C 15min \int 5min L : -40°C 15min	300 CYCLES	76 PCS		0/1
3	Thermal Shock	H : +100°C 5min \int 10 sec L : -10°C 5min	300 CYCLES	76 PCS		0/1
4	High Temperature Storage	TEMP:100°C	1000 HRS	76PCS		0/1
5	Low Temperature Storage	TEMP:-40°C	1000 HRS	76 PCS		0/1
6	DC Operating Life	TEMP:25°C I _f = 10mA	1000 HRS	76 PCS		0/1
7	High Temperature / High Humidity	85°C / 85% RH	1000 HRS	76 PCS		0/1

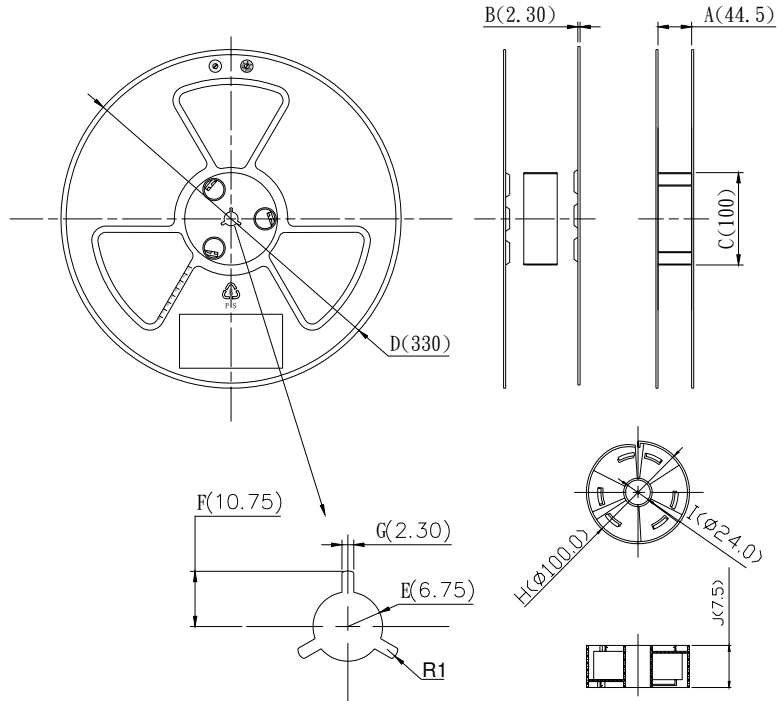
Note : I_{vt} : The test I_v value of the chip before the reliability test

I_v : The test value of the chip that has completed the reliability test

U : Upper Specification Limit

L : Lower Specification Limit

Package Dimensions



Taping Dimensions

